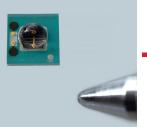


Infrared LED



L14097-0094GL

Surface mount type infrared LED with lens

The L14097-0094GL is an LED available in a surface mount type COB package with lens. High output was realized by using a large chip and heat dissipation board.

Features

- High output
- Compact, surface mount type package with lens (2.8 × 2.8 × 1.45^t mm)
- High reliability
- **■** Supports lead-free reflow soldering

Application

- Optical switches
- Near infrared lighting

■ Absolute maximum ratings (Ta=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Value	Unit
Reverse voltage	VR max		5	V
Forward current	IF max		1	Α
Forward current decrease rate	ΔIF	Ta > 25 °C	8	mA/°C
Pulse forward current	IFP max	Pulse width=10 µs Duty ratio=1%	3	А
Pulse forward current decrease rate	ΔIFP	Ta > 25 °C	24	mA/°C
Power dissipation	Pd max		3.5	W
Operating temperature	Topr	No dew condensation*1	-30 to +100	°C
Storage temperature	Tstg	No dew condensation*1	-40 to +125	°C
Junction temperature	Tj	*2	145	°C
Soldering temperature	Tsol		250 (twice)*3	°C

^{*1:} When there is a temperature difference between a product and the surrounding area in high humidity environment, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

➡ Electrical and optical characteristics (Ta=25 °C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Peak emission wavelength	λр	IF=50 mA	910	940	970	nm
Spectral half width	Δλ	IF=50 mA	-	40	-	nm
Radiant flux	Ι ΜΔ	IF=50 mA	42	60	-	mW
		IF=1000 mA*5	850	1200	-	
Radiant intensity	10	IF=50 mA	13	18	-	mW/sr
		IF=1000 mA*5	240	360	-	
Forward voltage	l \/⊏	IF=50 mA	-	2.5	3.0	V
		IF=1000 mA*5	-	3.0	4.0	
Reverse current	IR	VR=5 V	-	-	10	μA
Thermal resistance	Rth		-	15	-	°C/W
Cutoff frequency*4	fc	IF=50 mA \pm 1 mAp-p	5	10	-	MHz

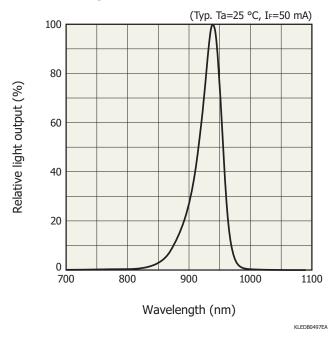
^{*4:} Frequency at which the optical output drops by 3 dB relative to the output at 100 kHz

^{*2:} Please allow sufficent heat dissipation on the mounting side.

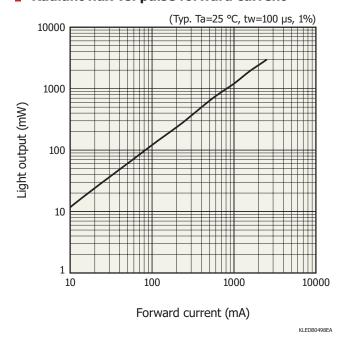
^{*3:} Reflow soldering, JEDEC J-STD-020 MSL 2a, see P.6

^{*5:} Pulse width=10 µs, Duty ratio=1%

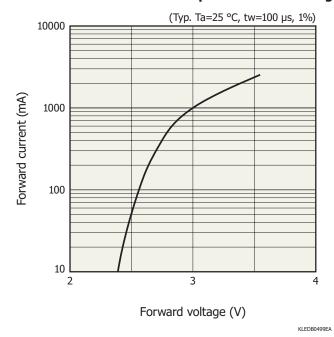
Emission spectrum



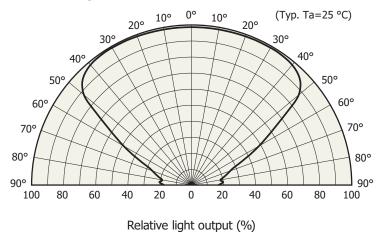
- Radiant flux vs. pulse forward current



Pulse forward current vs. pulse forward voltage

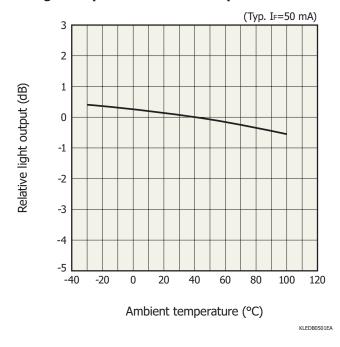


Directivity

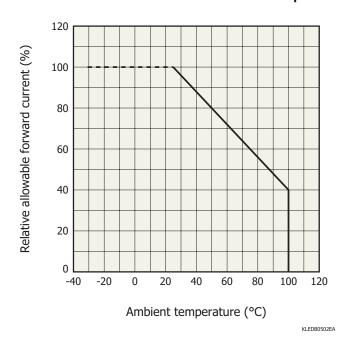


KLEDB0500EA

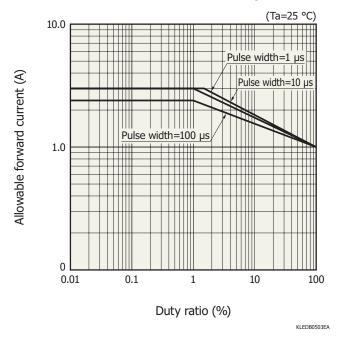
- Light output vs. ambient temperature



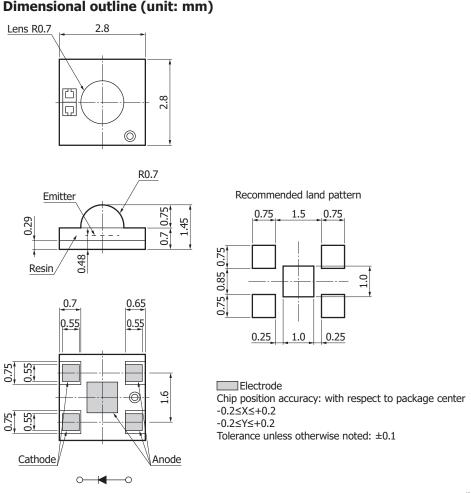
- Allowable forward current vs. ambient temperature



Allowable forward current vs. duty ratio



Dimensional outline (unit: mm)



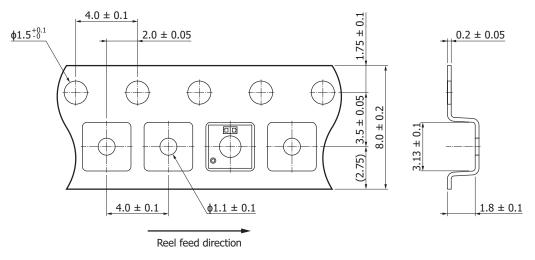
KLEDA0109EB

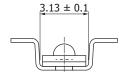
Standard packing specifications

■ Reel (conforms to JEITA ET-7200)

Outer diameter	Hub diameter	Tape width	Material	Electrostatic characteristics
φ180 mm	ф60 mm	8 mm	PS	Conductive

■ Embossed tape (unit: mm, material: PC, conductive)

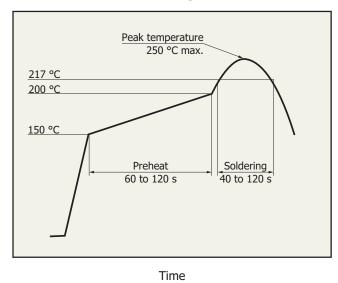




KLEDC0062EA

- Packing quantity 2000 pcs/reel
- Packing type
 Reel and desiccant in moisture-proof packaging (vaccum-sealed)

Recommended reflow soldering conditions



- · After unpacking, store the device in an environment at a temperature range of 5 to 30 °C and a humidity of 60% or less, and perform reflow soldering within 4 week.
- · The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

KLEDB0536EC

Baking

Femperature

If more than 3 months have passed in the unopend state or storage conditions are exceeded after opening the package, baking is required to remove moisture before reflow soldering. For the baking, refer to "Surface mount type products / precautions".

- Recommended baking conditions
- · Temperature: 150 °C, 3 hours, once

Note: Before you set baking conditions, check that problems do not occur in the product by testing out the conditions in advance.

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Surface mount type products
- Technical information
- · LED / Technical note

Information described in this material is current as of June 2021.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

The product warranty is valid for one year after delivery and is limited to product repair or replacement for defects discovered and reported to us within that one year period. However, even if within the warranty period we accept absolutely no liability for any loss caused by natural disasters or improper product use. Copying or reprinting the contents described in this material in whole or in part is prohibited without our prior permission.

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